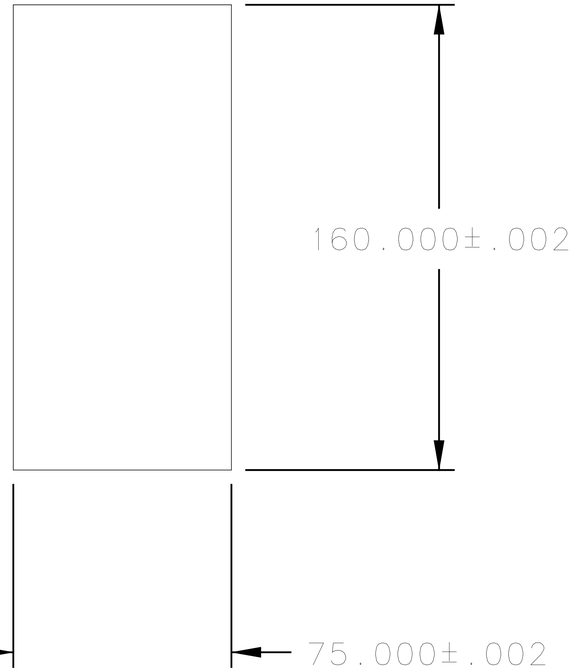
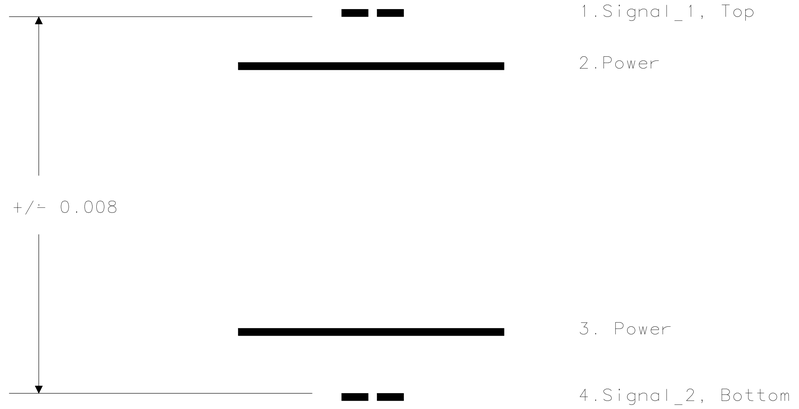
DWG.NO. 2866 | SH | REV. A





Board Characteristics - 4 LAYER BOARD

1. Material: FR4
2. Minimum trace width: 0.012" and clearence: 0.007"
4. 1 oz Copper
5. Electroless Nickel Immersion Gold plating, with min. Ni: 2.5-5 um; Au: 0.05-0.2 um. Apply Solder Mask over bare copper.
6. Board Thickness: 0.062 +/- 0.008
8. Silkscreen on Component and Solder Sides.
10. FHS tolerances: +/- 0.003 unless specified otherwise.
12. Zc=50 Ohm

BOARD's DRILL SCHEDULE

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Min/Max
○	.02	40	YES	---
⊞	.041	15	YES	---
⌀	.052	60	YES	---
⊟	.062	8	YES	---
⊖	.06496063	2	NO	---
◫	.067	12	YES	---
⊕	.075	48	YES	---
□	.10629921	4	YES	---

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES
TOLERANCES ARE:
FRACTIONS DECIMALS ANGLES
.XX
.XXX
DO NOT SCALE DRAWING

TREATMENT

FINISH

SIMILAR TO | ACT. WT | CALC WT

CONTRACT NO.

APPROVALS	DATE
DRAWN M.Bogdan	8/10/16
CHECKED M.Bogdan	8/10/16
ISSUED	

UNIVERSITY OF CHICAGO
ELECTRONICS DEVELOPMENT GROUP

TITLE
20-BIT ADC Board Tester
Specification Drawing

SIZE B | FSCM NO. | DWG. NO. 2881 | REV. A

SCALE 1/2 | SHEET

THIS SHEET IS COMPUTER GENERATED